

Description

The GT1003B uses advanced trench technology and design to provide excellent $R_{DS(ON)}$, low gate charge. This device is suitable for use in high frequency Synchronous rectification application.

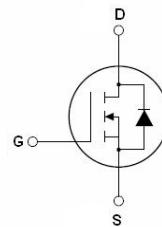
General Features

| V _{DSS} | R _{DS ON} @ 10V (Typ) | I _D |
|------------------|-----------------------------------|----------------|
| 100V | 115mΩ | 7 A |

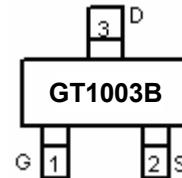
- High density cell design for ultra low Rdson
- Lead free product is acquired
- Excellent package for good heat dissipation
- RoHS Compliant

Application

- Consumer electronic power supply
- Isolated DC/DC converter
- Motor control



Schematic Diagram



Marking and Pin Assignment



SOT-23

Ordering Information

| Part Number | Marking | Case | Packaging |
|-------------|---------|--------|--------------|
| GT1003B | GT1003B | SOT-23 | 3000pcs/Reel |

Absolute Maximum Ratings (TA=25°C unless otherwise noted)

| Parameter | Symbol | Limit | Unit |
|--|-----------------------------------|------------|------|
| Drain-Source Voltage | V _{DS} | 100 | V |
| Gate-Source Voltage | V _{GS} | ±20 | V |
| Drain Current-Continuous | I _D | 7 | A |
| Drain Current-Pulsed (Note 1) | I _{DM} | 21 | A |
| Maximum Power Dissipation | P _D | 17 | W |
| Single pulsed avalanche energy (Note 5) | E _{AS} | 1.2 | mJ |
| Operating Junction and Storage Temperature Range | T _J , T _{STG} | -55 To 150 | °C |

Thermal Characteristic

| | | | |
|---|------------------|-----|------|
| Thermal Resistance, Junciton-case | R _{θJC} | 7.4 | °C/W |
| Thermal Resistance,Junction-to-Ambient (Note 2) | R _{θJA} | 62 | °C/W |

Electrical Characteristics (TA=25°C unless otherwise noted)

| Parameter | Symbol | Condition | Min | Typ | Max | Unit |
|---------------------------------|-------------------|---|-----|-----|-----|------|
| Off Characteristics | | | | | | |
| Drain-Source Breakdown Voltage | BV _{DSS} | V _{GS} =0V I _D =250μA | 100 | 110 | - | V |
| Zero Gate Voltage Drain Current | I _{DSS} | V _{DS} =100V,V _{GS} =0V | - | - | 1 | μA |

| | | | | | | |
|---|----------------------|--|---|------|------|----|
| Gate-Body Leakage Current | I _{GSS} | V _{GS} =±20V, V _{DS} =0V | - | - | ±100 | nA |
| On Characteristics (Note 3) | | | | | | |
| Gate Threshold Voltage | V _{GS(th)} | V _{DS} =V _{GS} , I _D =250μA | 1 | 1.95 | 3 | V |
| Drain-Source On-State Resistance | R _{DS(ON)} | V _{GS} =10V, I _D =3.5A | - | 115 | 140 | mΩ |
| Dynamic Characteristics (Note 4) | | | | | | |
| Input Capacitance | C _{iss} | V _{DS} =50V, V _{GS} =0V, F=1.0MHz | - | 206 | - | PF |
| Output Capacitance | C _{oss} | | - | 28.9 | - | PF |
| Reverse Transfer Capacitance | C _{rss} | | - | 1.4 | - | PF |
| Switching Characteristics (Note 4) | | | | | | |
| Turn-on Delay Time | t _{d(on)} | V _{DD} =50V, I _D =5A V _{GS} =10V, R _{GEN} =2Ω | - | 14.7 | - | ns |
| Turn-on Rise Time | t _r | | - | 3.5 | - | ns |
| Turn-Off Delay Time | t _{d(off)} | | - | 20.9 | - | ns |
| Turn-Off Fall Time | t _f | | - | 2.7 | - | ns |
| Total Gate Charge | Q _g | V _{DS} =50V, I _D =5A, V _{GS} =10V | - | 4.3 | - | nC |
| Gate-Source Charge | Q _{gs} | | - | 1.5 | - | nC |
| Gate-Drain Charge | Q _{gd} | | - | 1.1 | - | nC |
| Gate plateau voltage | V _{plateau} | | | 5.0 | | V |
| Drain-Source Diode Characteristics | | | | | | |
| Diode Forward Current (Note 2) | I _s | V _{GS} <V _{th} | - | - | 7 | A |
| Pulsed Source Current | I _{SP} | V _{GS} <V _{th} | | | 21 | |
| Diode Forward Voltage (Note 3) | V _{SD} | V _{GS} =0V, I _s =7A | - | - | 1.2 | V |
| Reverse Recovery Time | t _{rr} | I _F =5A, dI _F /dt = 100A/ μ s | | 32.1 | | nS |
| Reverse Recovery Charge | Q _{rr} | | | 39.4 | | μC |
| Peak Reverse Recovery Current | I _{rrm} | | - | 2.1 | - | A |

Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, t ≤ 10 sec.
3. Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 2%.
4. Guaranteed by design, not subject to production
5. VDD=50 V, RG=50 Ω, L=0.3 mH, starting Tj=25 ° C.

Typical Electrical And Thermal Characteristics

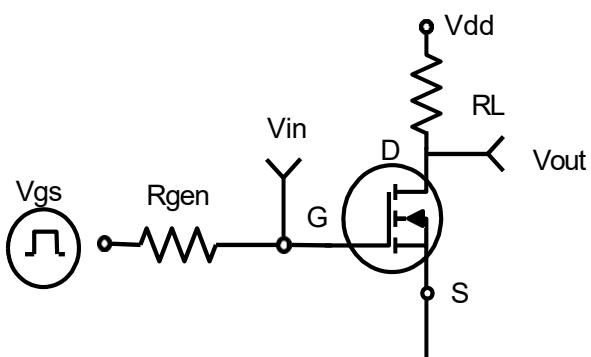


Figure 1. Switching Test Circuit

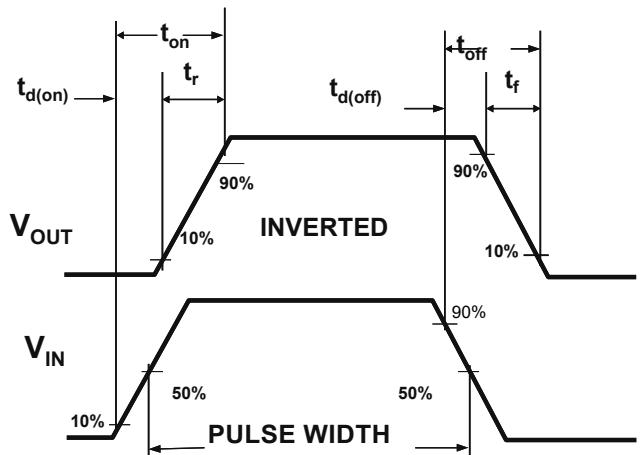


Figure 2. Switching Waveforms

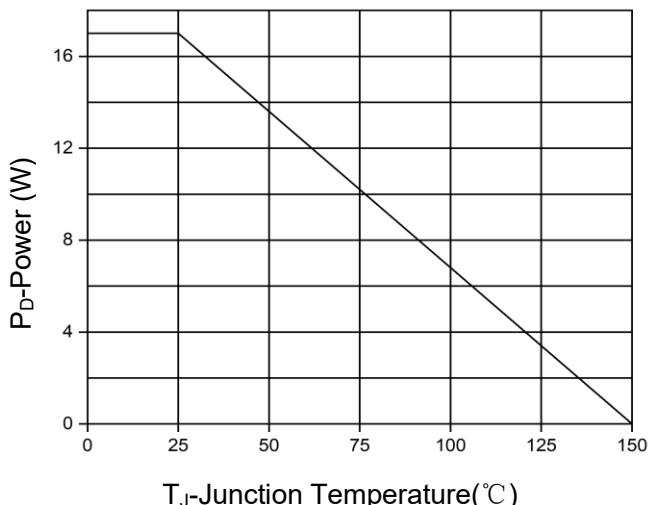


Figure 3. Power Dissipation

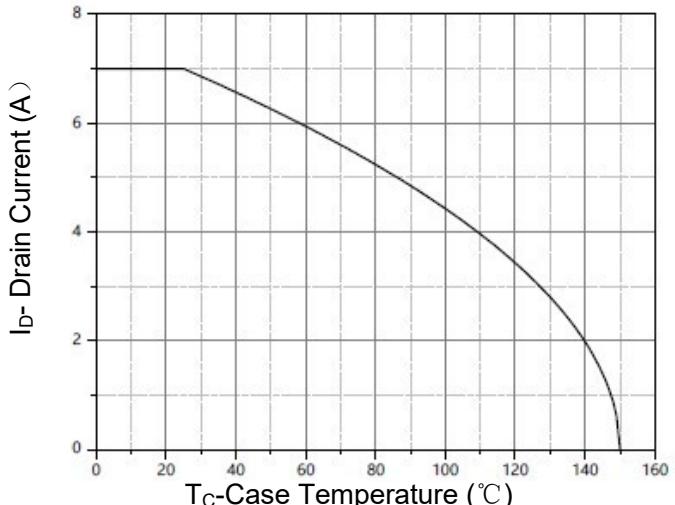


Figure 4. Drain Current

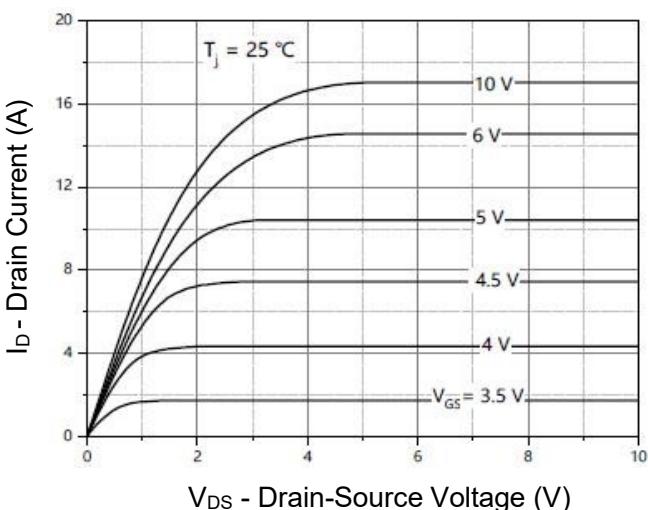


Figure 5. Output characteristics

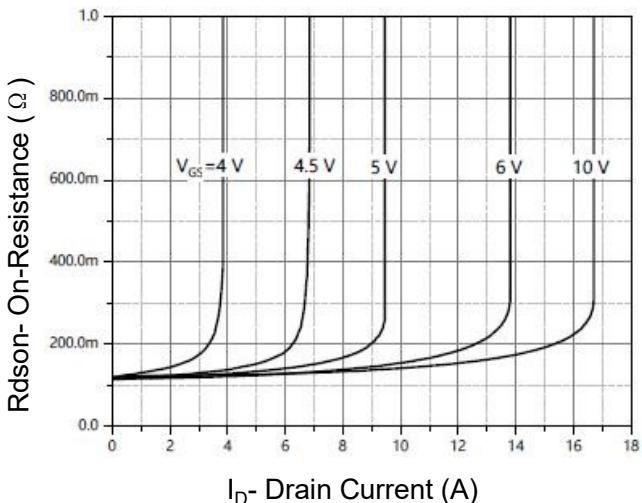


Figure 6. Drain-Source On-state resistance

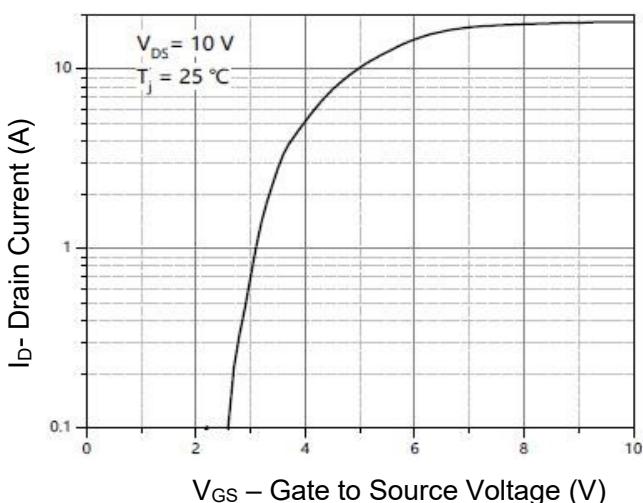


Figure 7. Transfer Characteristics

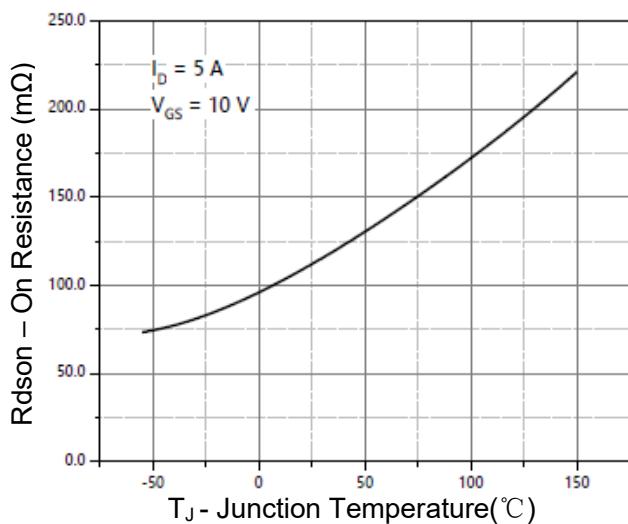


Figure 8. Drain-Source On-State Resistance

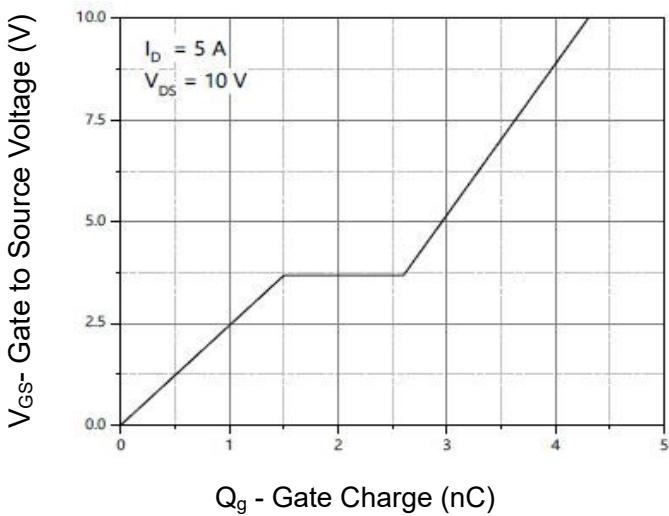


Figure 9. Gate Charge

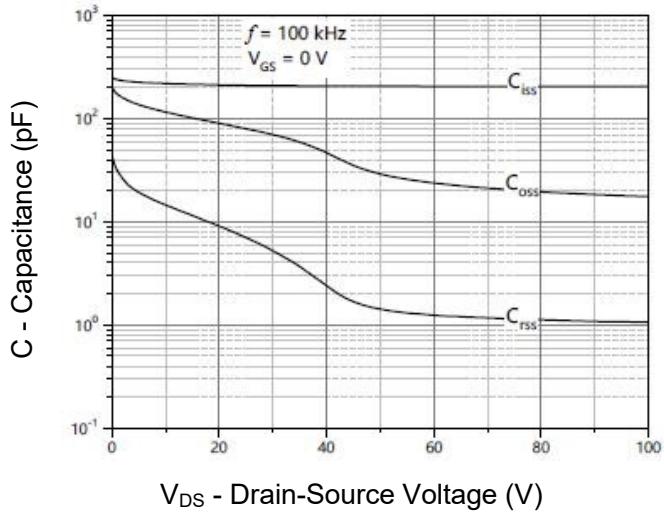


Figure 10. Capacitance vs Vds

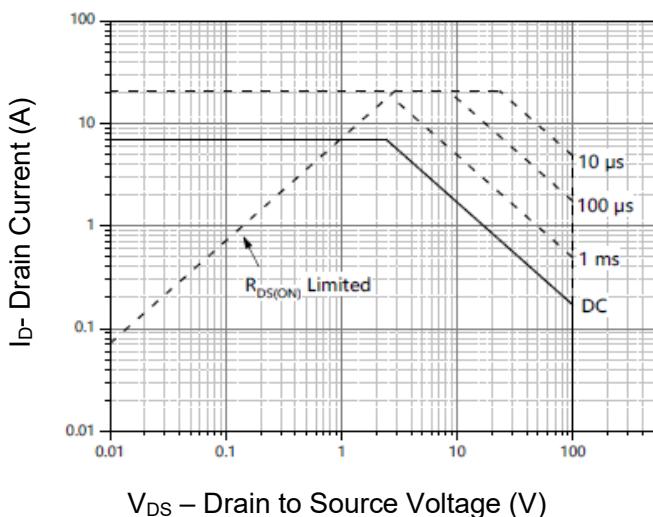


Figure 11. Safe Operation Area

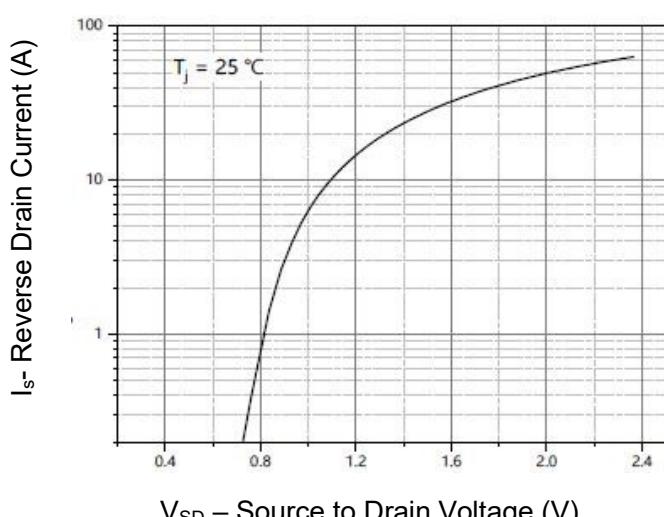
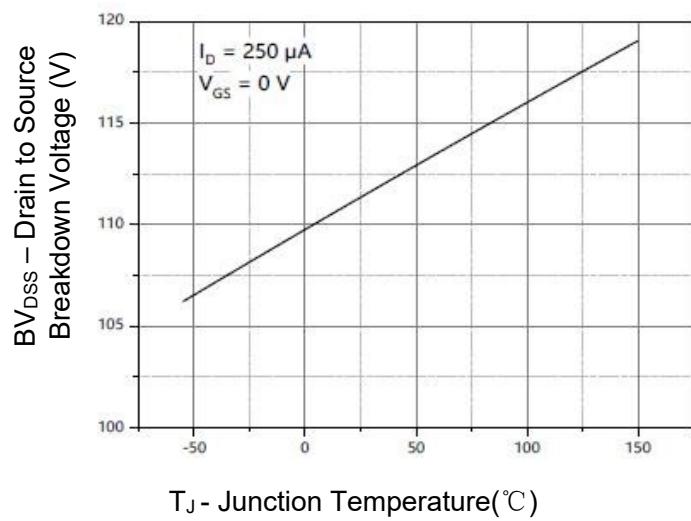
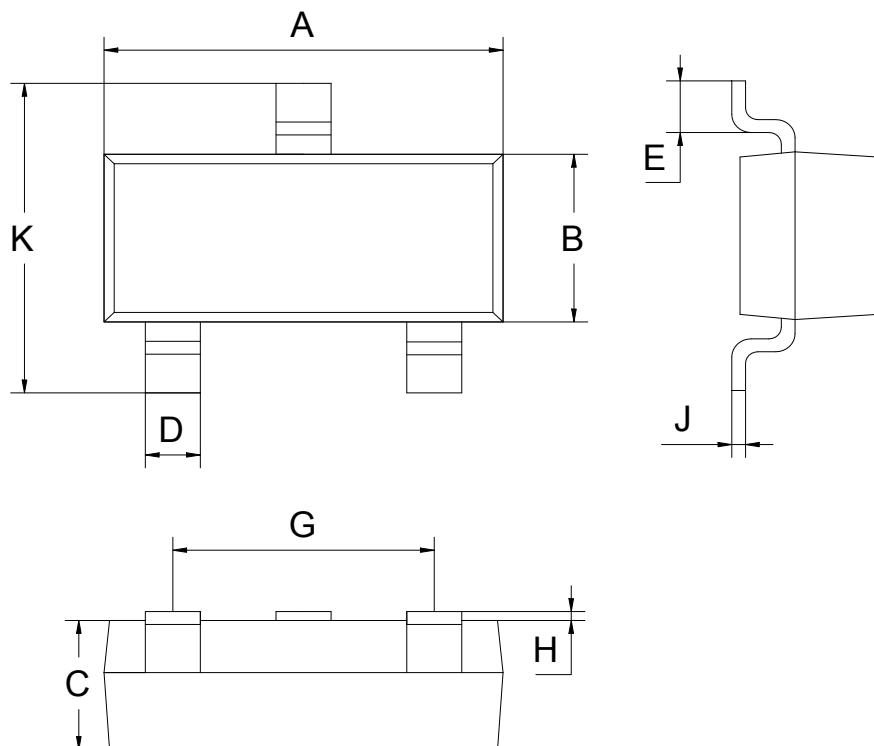


Figure 12. Source- Drain Diode Forward

**Figure 13. Drain-source breakdown voltage**

SOT-23 Package Information

| SOT-23 | | | |
|----------------------|---------|------|------|
| Dim | MIN | NOM | MAX |
| A | 2.80 | 2.90 | 3.00 |
| B | 1.20 | 1.30 | 1.40 |
| C | 0.90 | 1.00 | 1.10 |
| D | 0.39 | 0.40 | 0.45 |
| E | 0.20MIN | | |
| G | 1.90REF | | |
| H | 0.00 | - | 0.10 |
| J | 0.05 | 0.10 | 0.15 |
| K | 2.30 | 2.40 | 2.50 |
| All Dimensions in mm | | | |